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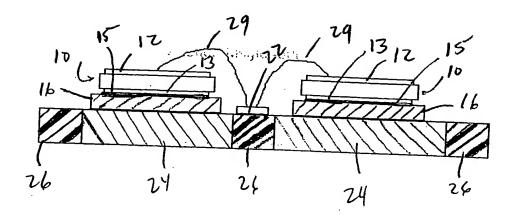
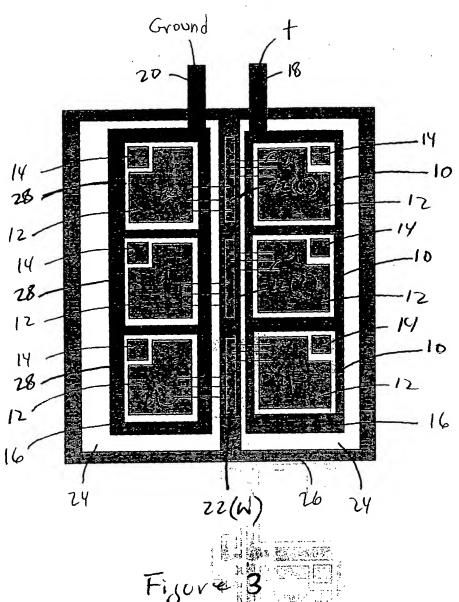


Figure 2

E. William

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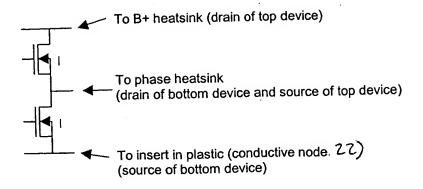


Figure 4a

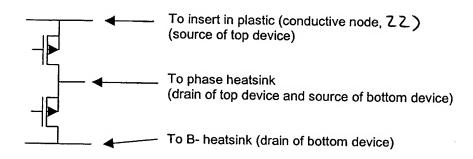


Figure 46

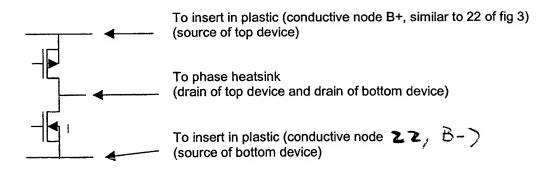
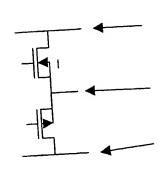


Figure 40



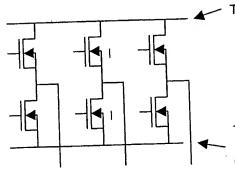
To B+ heatsink (drain of top device)

To insert in plastic (conductive node ZZ)

(source of top device and source of bottom device)

To B- heatsink (drain of bottom device)

Figure 4d



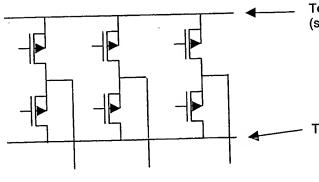
To single B+ heatsink (drain of top device)

To single insert in plastic (conductive node 22)

(source of bottom device)

To phase heatsinks (3 heatsinks) (drain of bottom device and source of top device)

Figure 5a

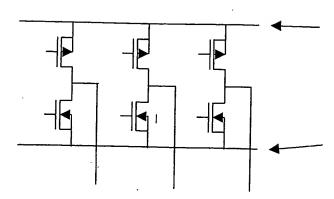


To single insert in plastic (conductive node ZZ) (source of top device)

To single B- heatsink (drain of bottom device)

To phase heatsinks (3 heatsinks) (drain of top device and source of bottom device)

Figure Sb

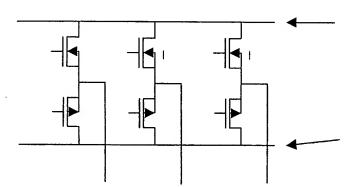


To single insert in plastic (conductive node 22/8+) (source of top devices)

To single insert in plastic (conductive node 22, B-) (source of bottom devices)

To phase heatsinks (drain of top device and drain of bottom device)

Figure Sc



To single B+ heatsink (drain of top device)

To single B- heatsink (drain of bottom device)

To inserts in plastic (total of 3) (conductive nodes 22) (source of top device and source of bottom device)

Figure 5d